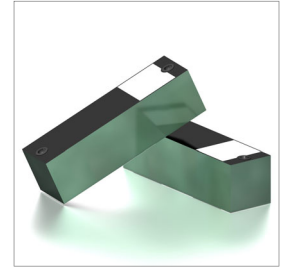


Features

- WiFi/ZigBee/Bluetooth
- Chip Type
- Stable And Reliable Performance
- 2400-2500MHz
- SMT Process Compatible

Applications

- ISM 2.4 GHz Applications
- ZigBee/BLE Applications
- Bluetooth Earphone Systems
- Smart Hand Held Devices
- Machine To Machine Communication



Part Numbering Guide

S AT CA 7A2A2A WF B1

SUNTSU

ANTENNA

CHIP ANTENNA

PACKAGE SIZE*

APPLICATION

FREQUENCY

7A2A2A = 7.0mm x 2.0mm x 2.0mm

WF - WiFi

B1 = 2400-2500MHz

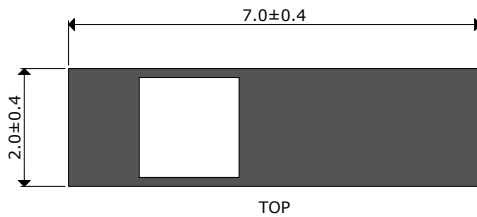


* Where letters denote decimal location (A=0, B=1, C=2, etc.); e.g. B5=0.15, 3A5=3.05, 9A=9.0

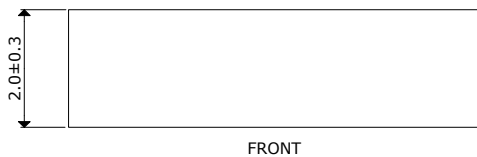
Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Band	MHz	2400		2500	
Impedance	Ω		50		
Polarization			Linear		
Peak Gain	dBi		2.3		At 2442MHz
Efficiency	%		67		At 2442MHz
VSWR				2	At Center Frequency
Operating Temperature	C	-40		85	

Outline Drawing

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



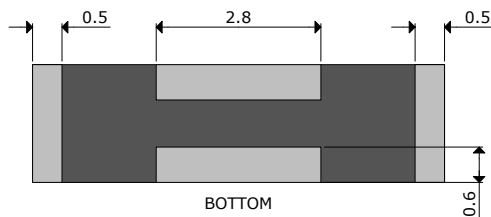
TOP



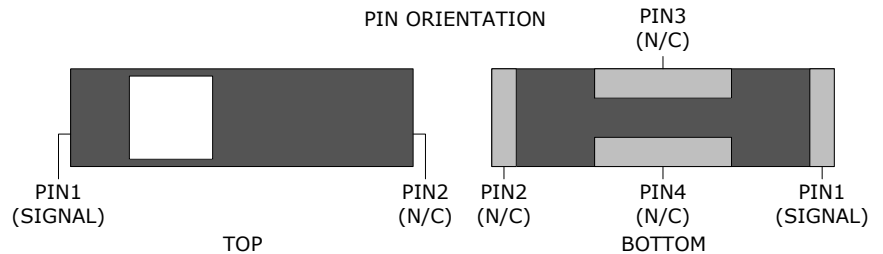
FRONT



SIDE



BOTTOM



PIN ORIENTATION

PIN3 (N/C)

PIN1 (SIGNAL)

PIN2 (N/C)

PIN2 (N/C)

PIN4 (N/C)

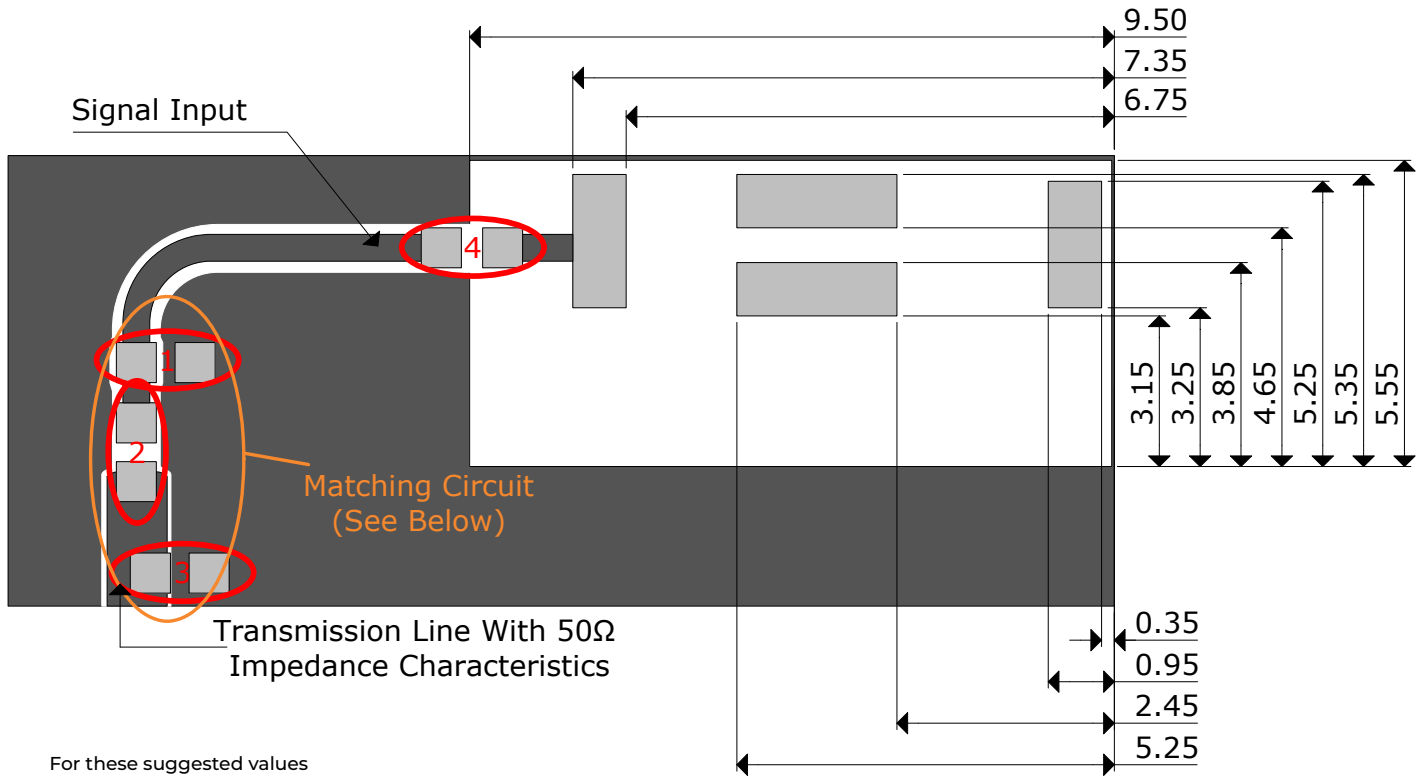
PIN1 (SIGNAL)

TOP

BOTTOM

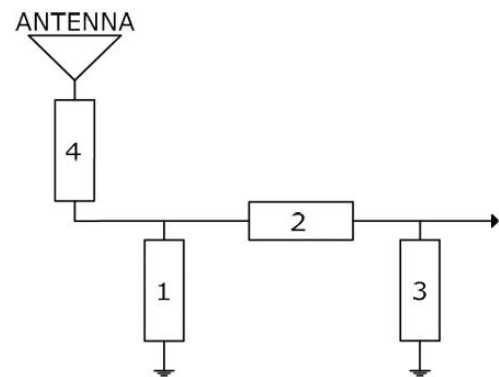
Recommended Land Pattern & Frequency Tuning Scenario Circuit

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



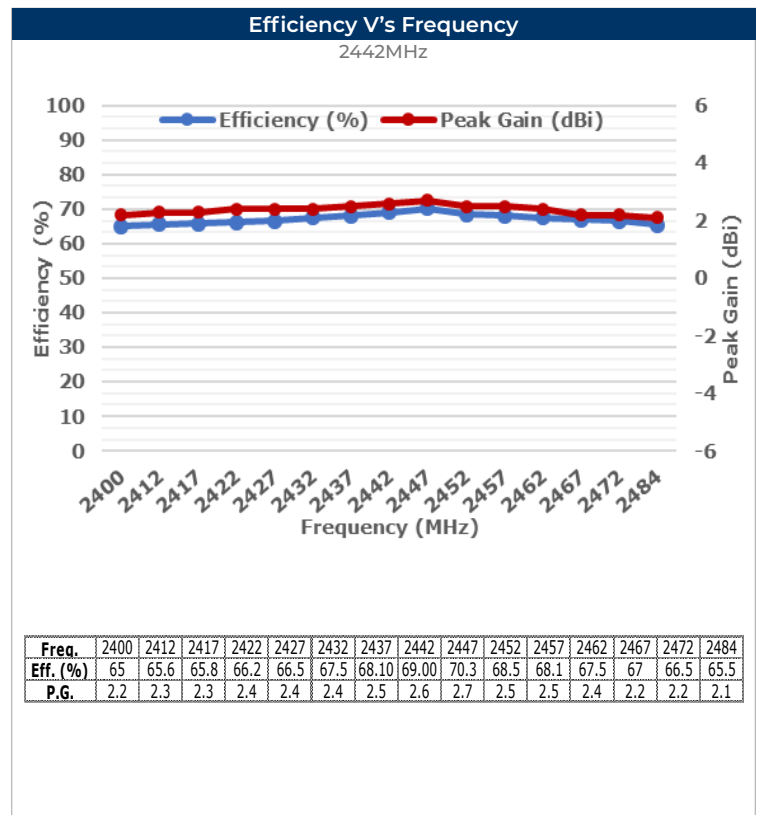
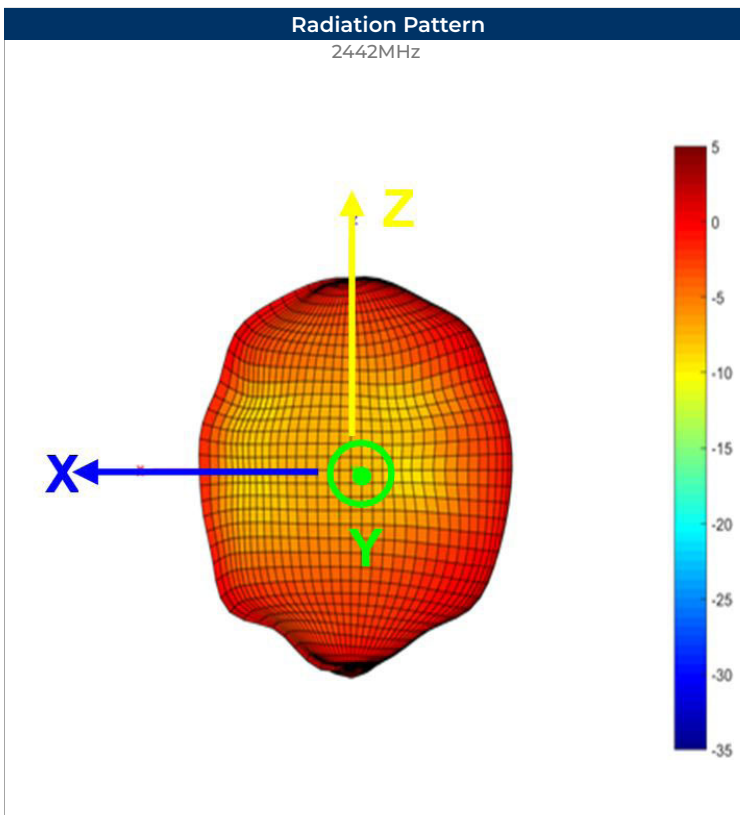
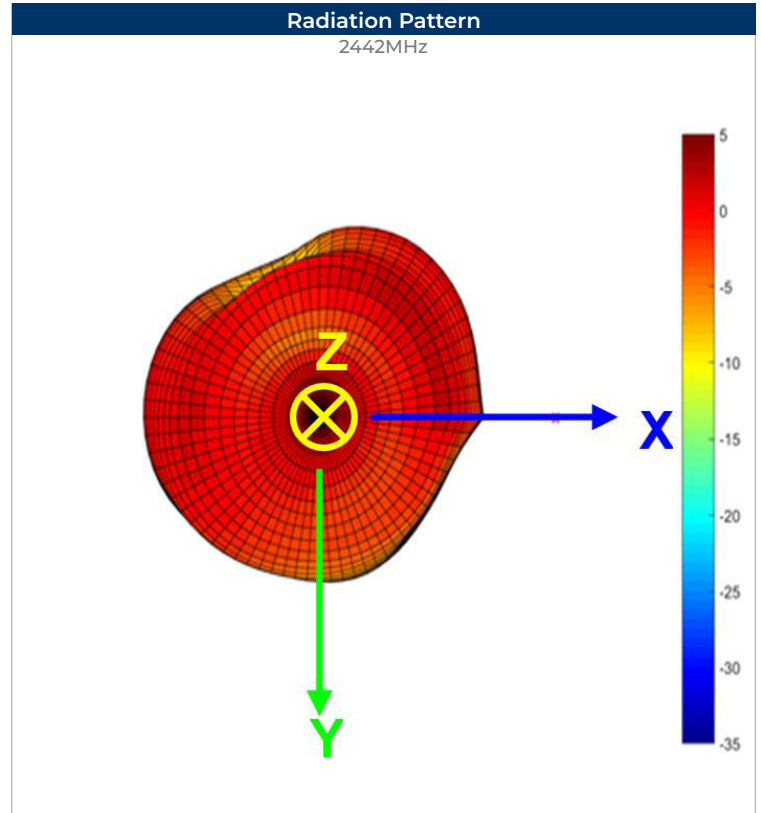
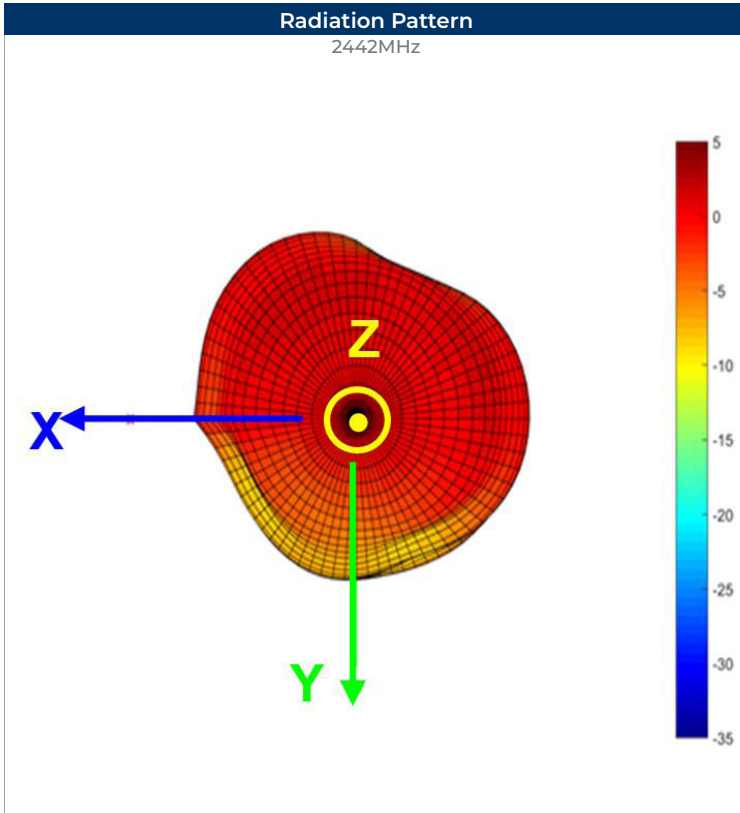
For these suggested values for the matching and tuning of components, the average frequency will be 2442MHz on a standard 49.5 x 20mm² Evaluation board.

Please note, these are average reference values which may need to be changed when different circuit boards or manufactures are used.



System Matching Circuit Components (915MHz Band)

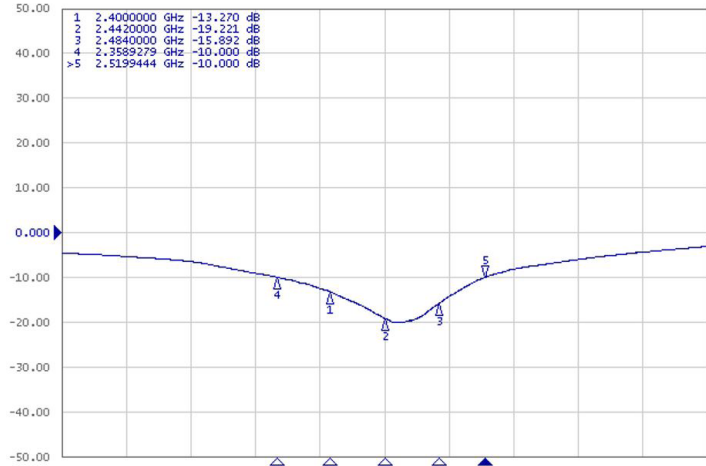
Location	Description	Vendor	Tolerance
1	1pF, (0402)	MURATA	±0.1pF
2	1.8nH, (0402)	MURATA	±0.1nH
3	N/A	-	-
4 (Fine Tuning)	5.6nH, (0402)	MURATA	±0.1nH



Electrical Test

Return Loss

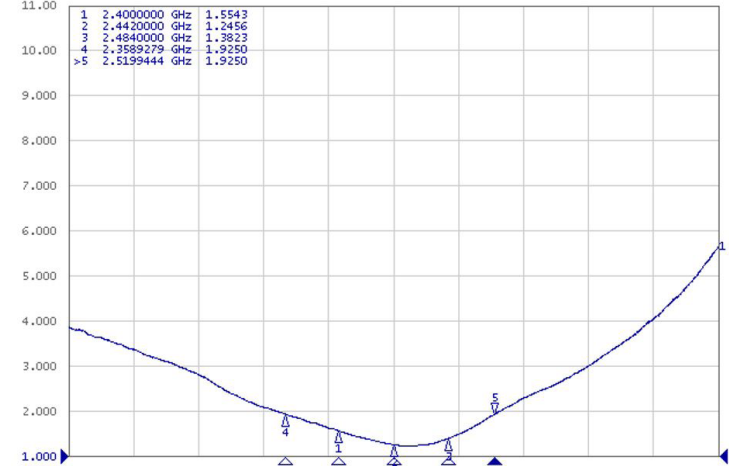
[F1] S11 Log Mag 10.00dB/ Ref 0.000dB [F2]



Electrical Test

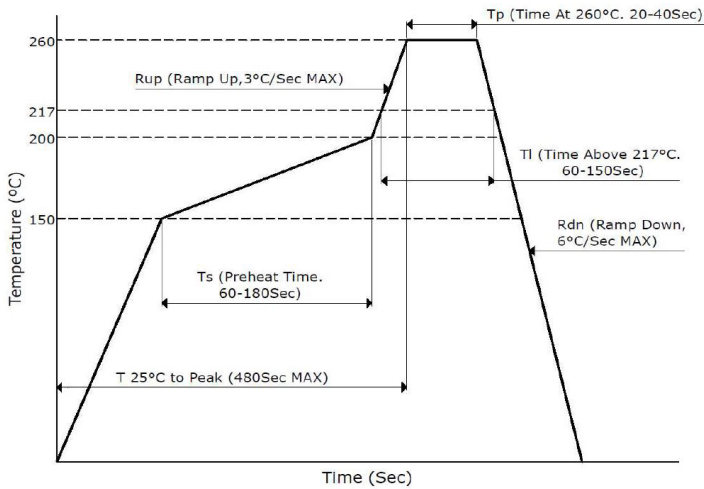
VSWR

[F1] S11 SWR 1.000/ Ref 1.000 [F2]



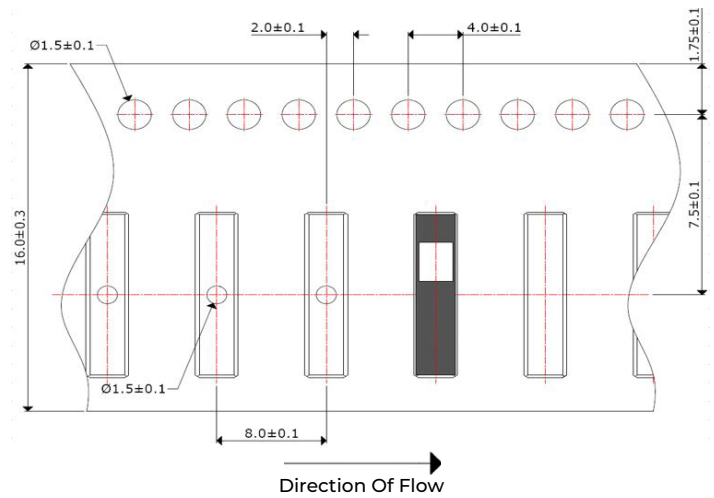
Soldering Conditions

Typical Soldering Profile For Lead-Free Process



Packaging - Tape And Reel

900Pcs / Reel



Environmental & Mechanical Specifications

High Temperature Test	85°C for 500 hours, and then to normal temperature/humidity for 24hours.
Low Temperature Test	-30°C for 500 hours, and then to normal temperature/humidity for 24hours.
Humidity Test	85°C / 90-95%RH for 96 hours, and then to normal temperature/humidity for 24hours.
Thermal Shock Test	-30°C for 30 min and +85°C for 30 min. 5 cycles, then expose to normal temperature/humidity for 24 hours or more.
Vibration Test	5 to 200 to 5Hz, swept in 10min, 4.5G at max(2mm amplitude), in X and Y directions for 2 hours each and in Z direction for 4 hours.